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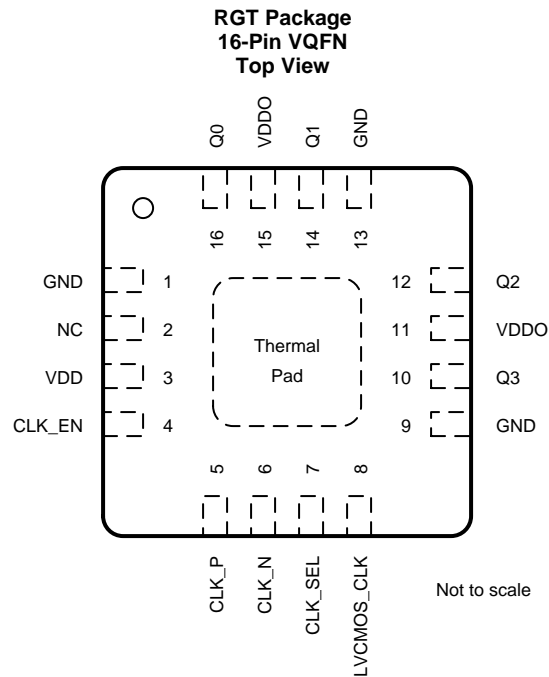
## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision A (June 2019) to Revision B	Page
• Changed part-to-part skew maximum from: 700 ps to: 550 ps	1
• Changed front long range radar application to: forward-facing long range radar	1
• Changed <i>Simplified Schematic</i> graphic	1
• Changed pin 2 in the RGT package from: OE to: NC	3
• Changed the pin descriptions	3
• Changed Changed CDM ESD ratings from: +/-250 V to: +/-750 V	4
• Added the <i>Typical Characteristics</i> section back to the data sheet	8
• Changed <i>Differential Input Level</i> timing diagram	9
• Changed the <i>Overview</i> section	10
• Changed <i>Functional Block Diagram</i>	10
• Added the <i>Typical Connection Diagram</i>	12
• Changed the <i>Power Considerations</i> section to <i>Power Dissipation Calculations</i>	16
• Moved the <i>Thermal Management</i> section to <i>Do's and Don'ts</i>	16
• Changed the recommendations for unused output pins	17
• Changed the <i>Input Slew Rate Considerations</i> section	17
• Added content to the <i>Ground Planes</i> section	18
• Changed the <i>Layout Example</i> section	19

Changes from Original (March 2019) to Revision A	Page
• Changed data sheet status from Advanced Information to Production Data	1

## 5 Pin Configuration and Functions



**Pin Functions<sup>(1)</sup>**

PIN		TYPE <sup>(2)</sup>	DESCRIPTION
NAME	NO.		
CLK_EN	4	I, PU	Synchronous clock enable input. CLK_EN must be held low until a valid reference clock is provided. Typically connected to VDD with an external 1-k $\Omega$ pullup. When unused, leave floating. 0 = Outputs are forced to logic low state 1 = Outputs are enabled with LVCMOS/LVTTL levels
CLK_N	6	I, PD, PU	Inverting differential clock input with internal 51-k $\Omega$ (typ) pullup resistor to VDD and internal 51-k $\Omega$ (typ) pulldown resistor to GND. Typically connected to the inverting clock input. When unused, leave floating. Internally biased to $V_{DD}/2$ when left floating.
CLK_P	5	I, PD	Noninverting differential clock input with internal 51-k $\Omega$ (typ) pulldown resistor to GND. Typically connected to the noninverting clock input. A single-ended clock input can also be connected to CLK_P. When unused, leave floating.
CLK_SEL	7	I, PU	Clock select input. Typically connected to VDD with an external 1-k $\Omega$ pullup. When unused, leave floating. 0 = Select LVCMOS_CLK (pin 8) 1 = Select CLK_P, CLK_N (pins 5, 6)
GND	1, 9, 13	G	Power supply ground.
LVCMOS_CLK	8	I, PD	Single-ended clock input with internal 51-k $\Omega$ (typ) pulldown resistor to GND. Typically connected to a single-ended clock input. When unused, leave floating. Accepts LVCMOS/LVTTL levels.
NC	2	NC	No connect pin. Typically left floating. Do not connect to GND.
Q0	16	O	Single-ended clock outputs with LVCMOS/LVTTL levels at 7- $\Omega$ output impedance. Typically connected to a receiver with a 43- $\Omega$ series termination. When unused, leave floating.
Q1	14		
Q2	12		
Q3	10		

(1) See [Recommendations for Unused Input and Output Pins](#), if applicable.

(2) G = Ground, I = Input, O = Output, P = Power, PU = 51-k $\Omega$  pullup, PD = 51-k $\Omega$  pulldown, NC = No connect

**Pin Functions<sup>(1)</sup> (continued)**

PIN		TYPE <sup>(2)</sup>	DESCRIPTION
NAME	NO.		
V <sub>DD</sub>	3	P	Power supply terminal. Typically connected to a 3.3-V supply. The VDD pin is typically connected GND with an external 0.1-uF capacitor.
V <sub>DDO</sub>	11, 15	P	Output supply terminals. Typically connected to a 3.3-V, 2.5-V, 1.8-V, or 1.5-V supply. The VDDO pins are typically connected GND with external 0.1-uF capacitors.

## 6 Specifications

### 6.1 Absolute Maximum Ratings<sup>(1)(2)</sup>

 Over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN	MAX	UNIT
V <sub>DD</sub>	Supply input voltage		−0.3	3.6	V
V <sub>DDO</sub>	Supply output voltage		−0.3	3.6	V
V <sub>I</sub>	Input voltage	CLK_EN, CLK_SEL, CLK_P, CLK_N, LVCMOS_CLK	−0.3	V <sub>DD</sub> + 0.3	V
	Input voltage	Q0, Q1, Q2, Q3	−0.3	V <sub>DDO</sub> + 0.3	V
T <sub>J</sub>	Junction temperature			150	°C
T <sub>stg</sub>	Storage temperature		−65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) If Military/Aerospace specified devices are required, contact the Texas Instruments Sales Office/Distributors for availability and specifications.

### 6.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 <sup>(1)</sup> HBM ESD Classification Level 2	±2000	V
		Charged-device model (CDM), per AEC Q100-011 CDM ESD Classification Level C5	±750	

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

### 6.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V <sub>DD</sub>	Supply input voltage	3.135	3.3	3.465	V
V <sub>DDO</sub>	Supply output voltage	3.135	3.3	3.465	V
		2.375	2.5	2.625	
		1.71	1.8	1.89	
		1.425	1.5	1.575	
T <sub>A</sub>	Ambient temperature	−40		125	°C
T <sub>J</sub>	Junction temperature	−40		135	°C
f <sub>OUT</sub>	Maximum output frequency <sup>(1)</sup>			350	MHz

- (1) There is no minimum input / output frequency provided the input slew rate is sufficiently fast. Refer to *Input Slew Rate Considerations*.

## 6.4 Thermal Information

THERMAL METRIC <sup>(1)(2)</sup>		LMK00804B-Q1	UNIT
		RGT (VQFN)	
		16 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	48.0	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	58.6	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	22.6	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	2.1	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	22.6	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	6.5	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report (SPRA953).
- (2) The package thermal impedance is calculated in accordance with JESD 51 and JEDEC2S2P (high-K board).

## 6.5 Power Supply Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified.

PARAMETER		MIN	TYP	MAX	UNIT
I <sub>DD</sub>	Power supply current through VDD			21	mA
I <sub>DDO</sub>	Power supply current through VDDO			5	mA

## 6.6 LVCMOS / LVTTTL DC Electrical Characteristics

 $V_{DD} = 3.3\text{ V} \pm 5\%$ ,  $V_{DDO} = 1.5\text{ V} \pm 5\%$ ,  $1.8\text{ V} \pm 5\%$ ,  $2.5\text{ V} \pm 5\%$ ,  $3.3\text{ V} \pm 5\%$  and  $T_A = -40^\circ\text{C}$  to  $125^\circ\text{C}$ 

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$V_{IH}$	Input high voltage	CLK_EN, CLK_SEL		2		$V_{DD} + 0.3$	V
		LVCNOS_CLK		2		$V_{DD} + 0.3$	V
$V_{IL}$	Input low voltage	CLK_EN, CLK_SEL		-0.3		0.8	V
		LVCNOS_CLK		-0.3		1.3	V
$I_{IH}$	Input high current	CLK_EN, CLK_SEL	$V_{IH} = V_{DD}$			15	$\mu\text{A}$
		LVCNOS_CLK	$V_{DD} = 3.465\text{ V}$ , $V_{IN} = 3.465\text{ V}$			150	$\mu\text{A}$
$I_{IL}$	Input low current	CLK_EN, CLK_SEL	$V_{IL} = \text{GND}$	-150			$\mu\text{A}$
		LVCNOS_CLK	$V_{DD} = 3.465\text{ V}$ , $V_{IN} = 0\text{ V}$	-150			$\mu\text{A}$
$V_{OH}$	Output high voltage <sup>(1)</sup>	$V_{DDO} = 3.3\text{ V} \pm 5\%$		2.64			V
		$V_{DDO} = 2.5\text{ V} \pm 5\%$		2			V
		$V_{DDO} = 1.8\text{ V} \pm 5\%$		1.44			V
		$V_{DDO} = 1.5\text{ V} \pm 5\%$		1.2			V
$V_{OL}$	Output low voltage <sup>(1)</sup>	$V_{DDO} = 3.3\text{ V} \pm 5\%$				0.66	V
		$V_{DDO} = 2.5\text{ V} \pm 5\%$				0.5	V
		$V_{DDO} = 1.8\text{ V} \pm 5\%$				0.36	V
		$V_{DDO} = 1.5\text{ V} \pm 5\%$				0.3	V
$I_{OZL}$	Output Hi-Z current low			-5			$\mu\text{A}$
$I_{OZH}$	Output Hi-Z current high					5	$\mu\text{A}$

(1) Outputs terminated with  $50\ \Omega$  to  $V_{DDO}/2$ .

## 6.7 Differential Input DC Electrical Characteristics

 $V_{DD} = 3.3\text{ V} \pm 5\%$ ,  $V_{DDO} = 1.5\text{ V} \pm 5\%$ ,  $1.8\text{ V} \pm 5\%$ ,  $2.5\text{ V} \pm 5\%$ ,  $3.3\text{ V} \pm 5\%$  and  $T_A = -40^\circ\text{C}$  to  $125^\circ\text{C}$ 

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$V_{ID}$	Differential input voltage swing, $(V_{IH} - V_{IL})^{(1)}$			0.15		1.4	V
$V_{IC}$	Input common-mode voltage <sup>(1)(2)</sup>			0.5		$V_{DD} - 0.85$	V
$I_{IH}$	Input high current <sup>(3)</sup>	CLK_N, CLK_P	$V_{DD} = 3.465\text{ V}$ , $V_{IN} = 3.465\text{ V}$			150	$\mu\text{A}$
$I_{IL}$	Input low current <sup>(3)</sup>	CLK_N, CLK_P	$V_{DD} = 3.465\text{ V}$ , $V_{IN} = 0\text{ V}$	-150			$\mu\text{A}$

(1)  $V_{IL}$  should not be less than  $-0.3\text{ V}$ .

(2) Input common-mode voltage is defined as  $V_{IH}$ .

(3) For  $I_{IH}$  and  $I_{IL}$  measurements on CLK\_P or CLK\_N, one must comply with  $V_{ID}$  and  $V_{IC}$  specifications by using the appropriate bias on CLK\_N or CLK.

## 6.8 Switching Characteristics

 $V_{DD} = 3.3\text{ V} \pm 5\%$ ,  $V_{DDO} = 1.5\text{ V} \pm 5\%$ ,  $1.8\text{ V} \pm 5\%$ ,  $2.5\text{ V} \pm 5\%$ ,  $3.3\text{ V} \pm 5\%$  and  $T_A = -40^\circ\text{C}$  to  $125^\circ\text{C}$ 

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$t_{PDH}$	Propagation delay, Low-to-high	LVC MOS_CLK <sup>(1)</sup> , CLK_P/CLK_N <sup>(2)</sup>	$-40^\circ\text{C}$ to $125^\circ\text{C}$	1		2.5	ns
$t_{SK(O)}$	Output skew <sup>(3)(4)</sup>	Measured on rising edge				35	ps
$t_{SK(PP)}$	Part-to-part skew <sup>(4)(5)</sup>					550	ps
$t_R/t_F$	Output rise/fall time	20% to 80%, $C_L = 5\text{ pF}$		100	310	600	ps
$t_{JIT}$	Additive jitter <sup>(6)</sup>	$f = 40\text{ MHz}$ , Input slew rate = $1.25\text{ V/ns}$ , 12-kHz to 20-MHz integration band			115	200	fs RMS
$PN_{FLOOR}$	Phase noise floor <sup>(7)</sup>	$f = 40\text{ MHz}$ , Input slew rate = $1.25\text{ V/ns}$	10-kHz offset		–151		dBc/Hz
			100-kHz offset		–160		
			1-MHz offset		–162		
			10-MHz offset		–162		
			20-MHz offset		–162		
$D_O$	Output duty cycle	REF = CLK_P/CLK_N, 50% input duty cycle, $f < 166\text{ MHz}$		45%		55%	
		REF = LVC MOS_CLK, 50% input duty cycle, $f > 166\text{ MHz}$		42%		58%	

- (1) Measured from the  $V_{DD}/2$  of the input to the  $V_{DDO}/2$  of the output.
- (2) Measured from the differential input crossing point to  $V_{DDO}/2$  of the output.
- (3) Defined as skew between outputs at the same supply voltage and with equal loading conditions. Measured at  $V_{DDO}/2$  of the output.
- (4) Parameter is defined in accordance with JEDEC Standard 65.
- (5) Calculation for part-to-part skew is the difference between the fastest and slowest  $t_{PD}$  across multiple devices, various supply voltages, operating at the same frequency, same temperature, with equal load conditions, and using the same type of inputs on each device.
- (6) Buffer additive jitter:  $t_{JIT} = \text{SQRT}(t_{JIT\_SYS}^2 - t_{JIT\_SOURCE}^2)$ , where  $t_{JIT\_SYS}$  is the RMS jitter of the system output (source+buffer) and  $t_{JIT\_SOURCE}$  is the RMS jitter of the input source, and system output noise is not correlated to the input source noise. Additive jitter should be considered only when the input source noise floor is 3 dB or better than the buffer noise floor ( $PN_{FLOOR}$ ). This is usually the case for high-quality, ultra-low-noise oscillators. Refer to [System-Level Phase Noise and Additive Jitter Measurement](#) for input source and measurement details.
- (7) Buffer phase noise floor:  $PN_{FLOOR} (\text{dBc/Hz}) = 10 \times \log_{10}[10^{(PN_{SYSTEM}/10)} - 10^{(PN_{SOURCE}/10)}]$ , where  $PN_{SYSTEM}$  is the phase noise floor of the system output (source+buffer) and  $PN_{SOURCE}$  is the phase noise floor of the input source. Buffer Phase Noise Floor should be considered only when the input source noise floor is 3 dB or better than the buffer noise floor ( $PN_{FLOOR}$ ). This is usually the case for high-quality, ultra-low-noise oscillators. Refer to [System-Level Phase Noise and Additive Jitter Measurement](#) for input source and measurement details.

## 6.9 Pin Characteristics

		MIN	TYP	MAX	UNIT
$C_I$	Input capacitance		1		pF
$R_{PU}$	Input pullup resistance		51		k $\Omega$
$R_{PD}$	Input pulldown resistance		51		k $\Omega$
$C_{PD}$	Power dissipation capacitance (per output)		2		pF
$R_{OUT}$	Output impedance		7		$\Omega$

## 6.10 Typical Characteristics

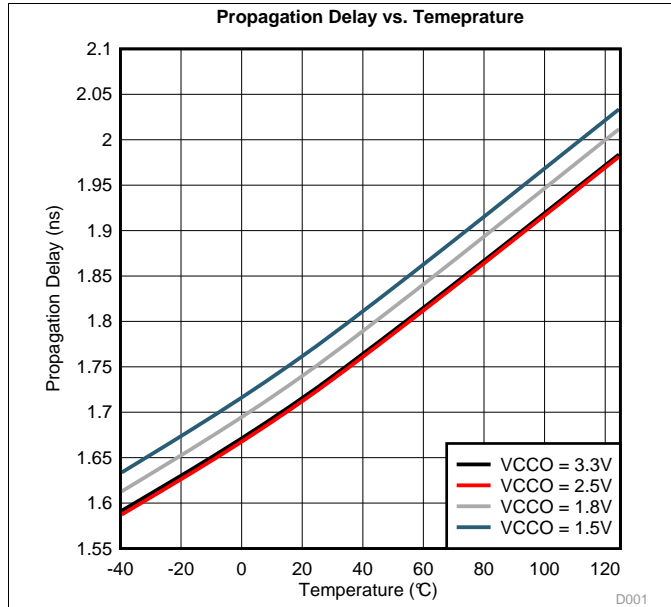


Figure 1. Propagation Delay vs. Temperature and Supply Voltage

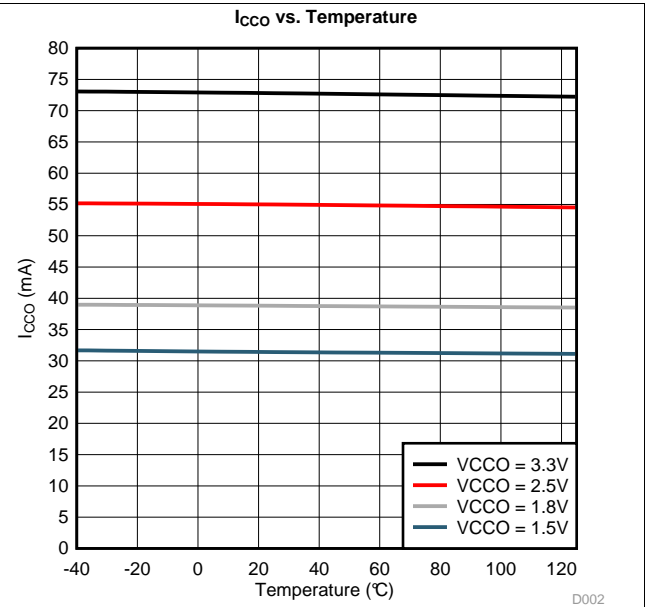


Figure 2. Icco vs. Temperature and Supply Voltage

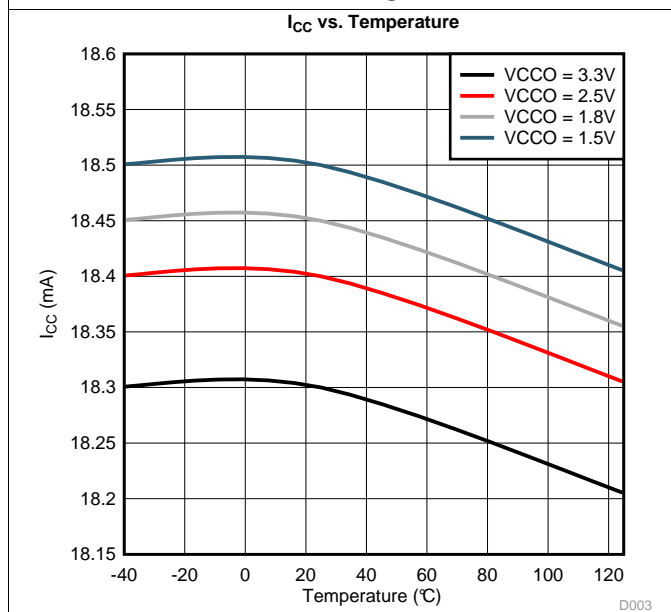


Figure 3. ICC vs. Temperature and Supply Voltage

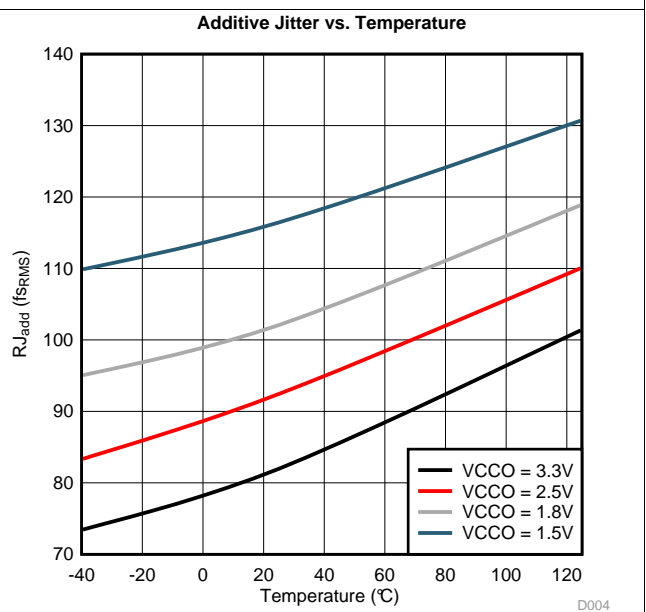
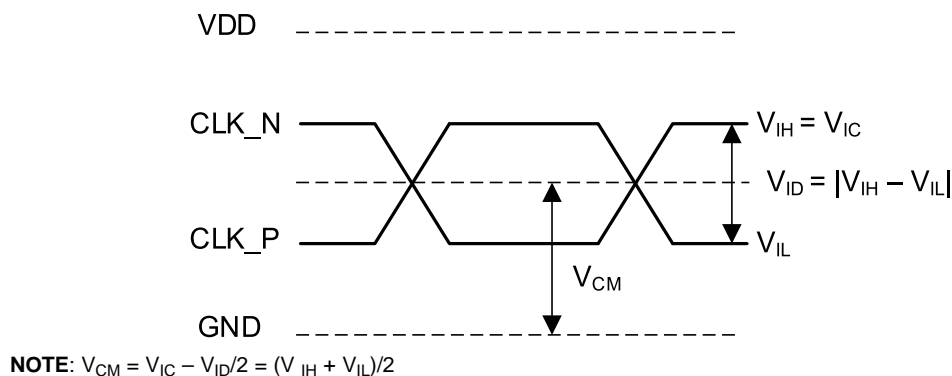


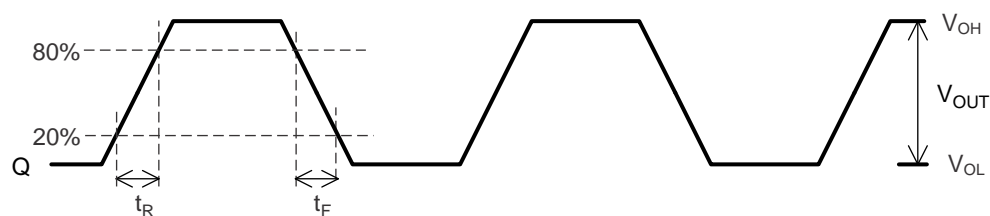
Figure 4. Additive Jitter vs. Temperature and Supply Voltage



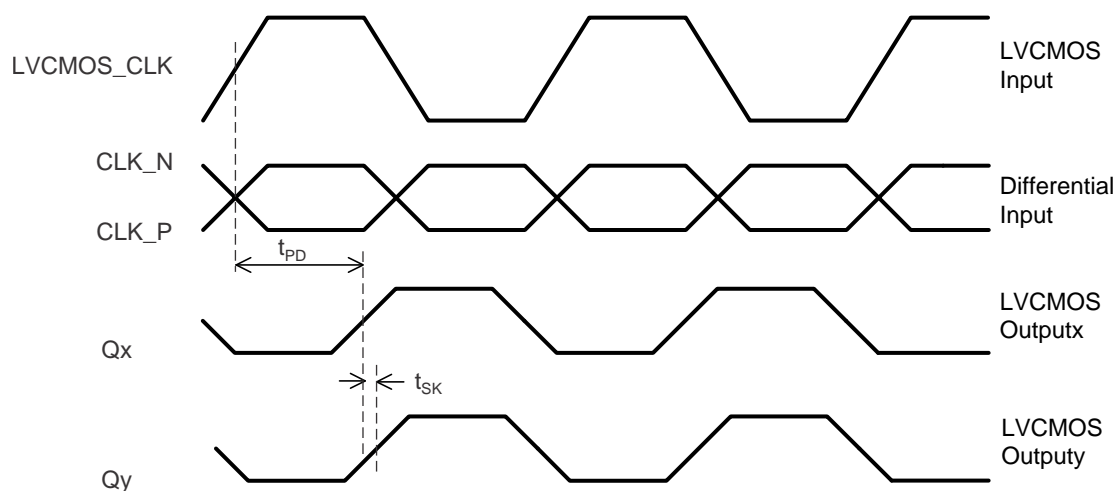
## 7 Parameter Measurement Information



**Figure 5. Differential Input Level**



**Figure 6. Output Voltage, and Rise and Fall Times**



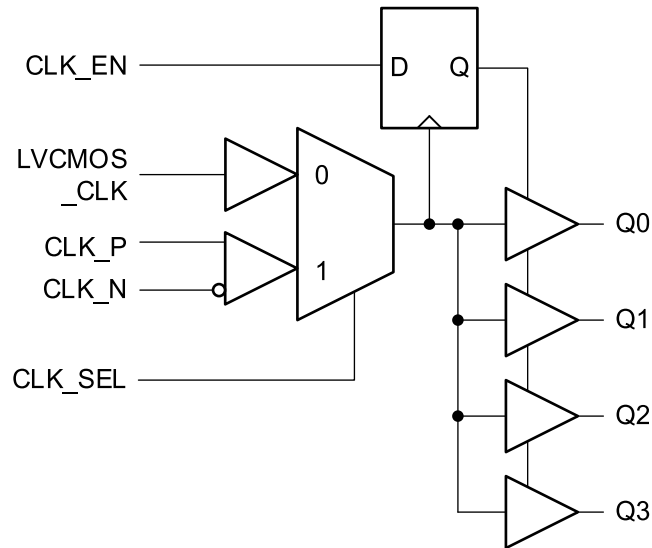
**Figure 7. Output Skew and Propagation Delay**

## 8 Detailed Description

### 8.1 Overview

The LMK00804B-Q1 is a clock fan-out buffer with two selectable clock inputs and four LVCMOS outputs. The LVCMOS\_CLK input accepts a single-ended clock input, and the CLK\_P/CLK\_N input accepts a differential or single-ended clock input. The LMK00804B-Q1 has a synchronous clock enable feature that allows the device to synchronously enable or disable the outputs using the CLK\_EN pin.

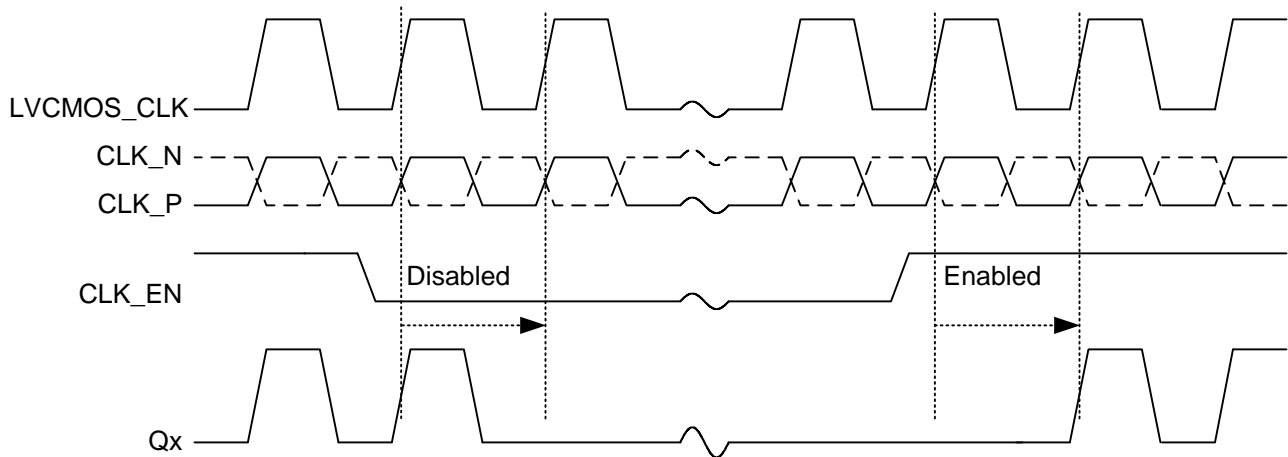
### 8.2 Functional Block Diagram



## 8.3 Feature Description

### 8.3.1 Clock Enable Timing

After CLK\_EN switches, the clock outputs are disabled or enabled following a rising and falling input clock edge as shown in Figure 8.



**Figure 8. Clock Enable Timing Diagram**

## 8.4 Device Functional Modes

The device can provide fan-out and level translation from a differential or single-ended input to a LVCMOS/LVTTL output where the output  $V_{OH}$  and  $V_{OL}$  levels are applied to the  $V_{DDO}$  pin and output load condition.

## 9 Applications and Implementation

### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

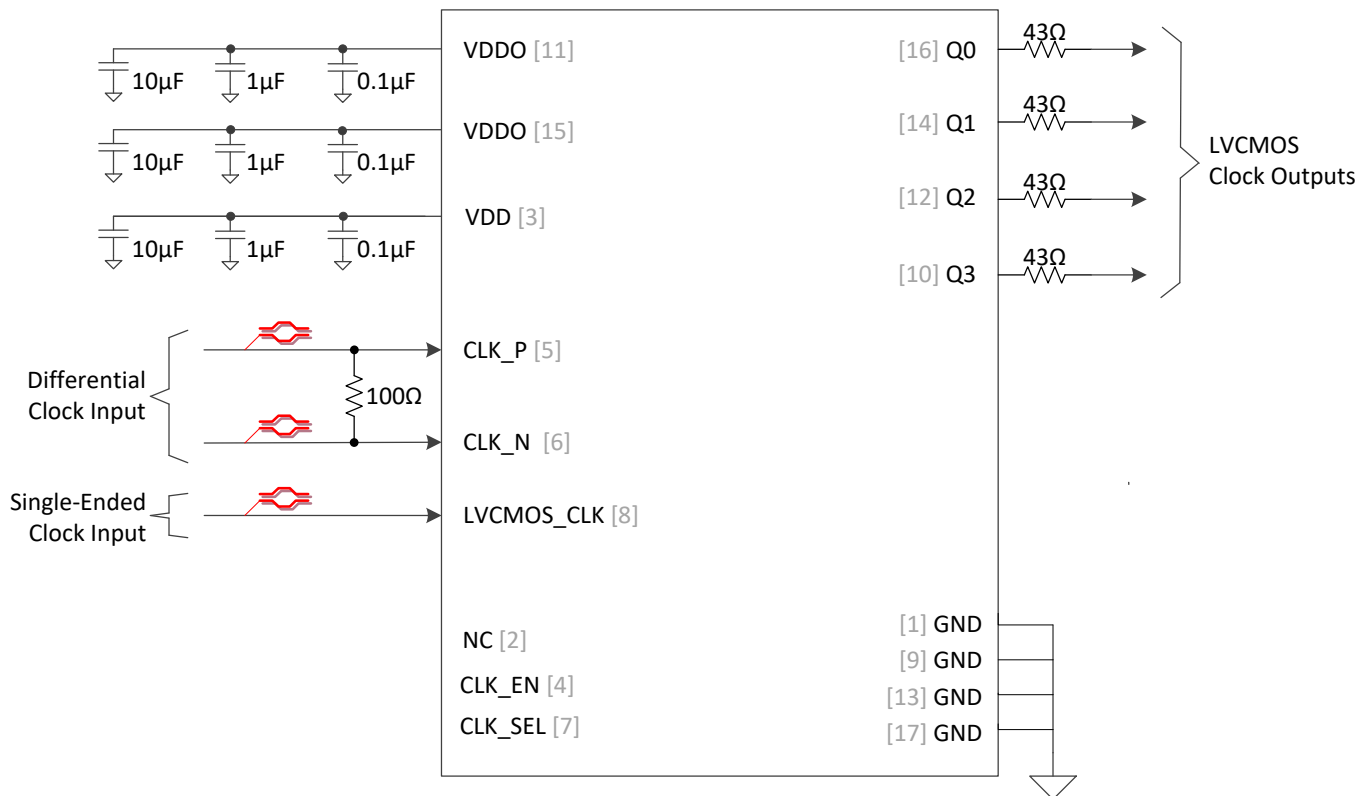
### 9.1 Application Information

The LMK00804B-Q1 enables the distribution of up to four LVCMOS copies of a low-noise source designed for general-purpose and high-performance applications. For best jitter performance, TI recommends to use the appropriate matching networks for the clock driver and receiver format, as detailed in the [Typical Applications](#) section. Practice good high-speed layout design outlined in the [High-speed Layout Guidelines](#) application report (SCAA082).

The LMK00804B-Q1 is designed to drive 50- $\Omega$  controlled-impedance traces. TI recommends to design these clock traces as 50- $\Omega$ , single-ended controlled impedance traces. Use a series 43- $\Omega$  resistor at the clock outputs Q[3:0] to match the driver impedance and series resistance to the trace impedance.

### 9.2 Typical Applications

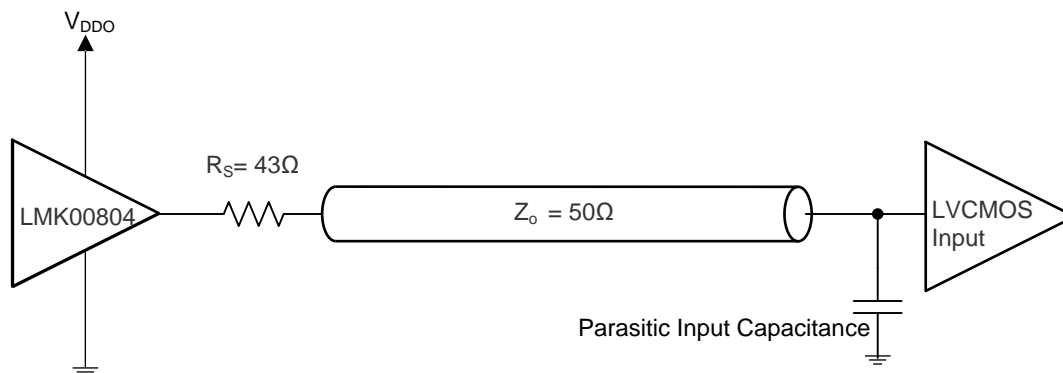
Refer to the following sections for output clock and input clock interface circuits.



**Figure 9. Typical Connection Diagram**

## Typical Applications (continued)

### 9.2.1 Output Clock Interface Circuit



**Figure 10. LVCMOS Output Configuration**

#### 9.2.1.1 Design Requirements

For high-performance devices, limitations of the equipment can affect phase-noise measurements. The noise floor of the equipment is often higher than the noise floor of the device. The real noise floor of the device is probably lower. It is important to understand that system-level phase noise measured at the DUT output is influenced by the input source and the measurement equipment.

For [Figure 11](#) and system-level phase noise plots, a Rohde & Schwarz SMA100A low-noise signal generator was cascaded with an Agilent 70429A K95 single-ended-to-differential converter block with ultra-low phase noise and fast-edge slew rate ( $>3$  V/ns) to provide a low-noise clock input source to the LMK00804B-Q1. An Agilent E5052 source signal analyzer with an ultra-low measurement noise floor was used to measure the phase noise of the input source (SMA100A + 70429A K95) and system output (input source + LMK00804B-Q1). The light blue trace shows the input source phase noise, and the dark blue trace in [Figure 11](#) shows the system output phase noise.

## Typical Applications (continued)

### 9.2.1.2 Detailed Design Procedure

Use Equation 1 to calculate the additive phase noise or noise floor of the buffer (PN<sub>FLOOR</sub>):

$$PN_{FLOOR} \text{ (dBc/Hz)} = 10 \times \log_{10}[10^{(PN_{SYSTEM}/10)} - 10^{(PN_{SOURCE}/10)}]$$

where

- PN<sub>SYSTEM</sub> is the phase noise of the system output (source+buffer)
  - PN<sub>SOURCE</sub> is the phase noise of the input source
- (1)

Use Equation 2 to calculate the additive jitter of the buffer (t<sub>JIT</sub>):

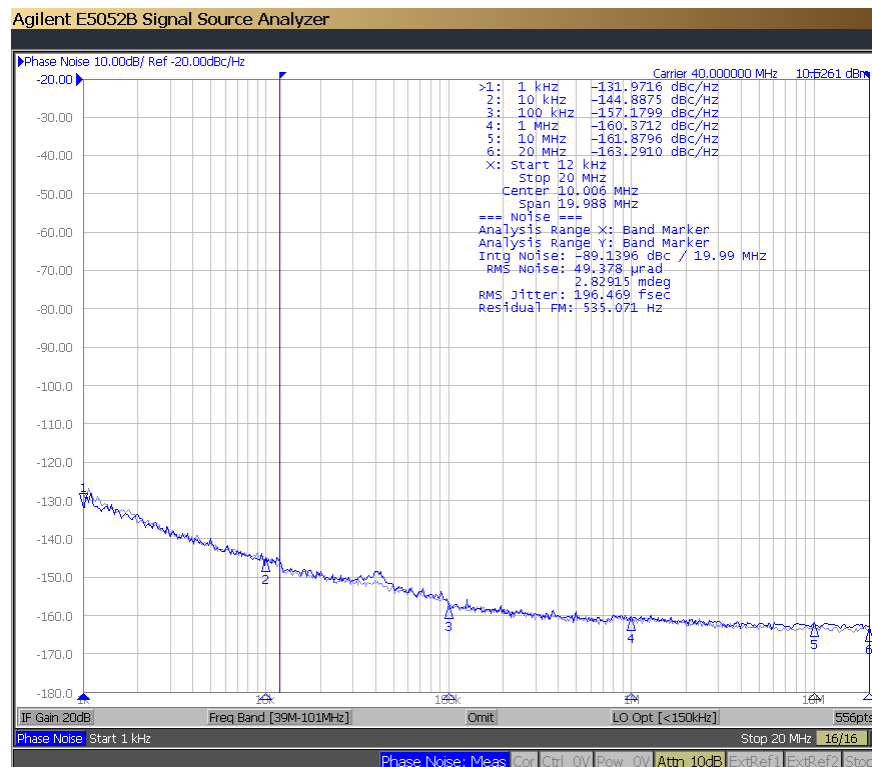
$$t_{JIT} = \text{SQRT}(t_{JIT\_SYS}^2 - t_{JIT\_SOURCE}^2)$$

where:

- t<sub>JIT\_SYS</sub> is the RMS jitter of the system output (source+buffer), integrated from 10 kHz to 20 MHz
  - t<sub>JIT\_SOURCE</sub> is the RMS jitter of the input source, integrated from 10 kHz to 20 MHz
- (2)

### 9.2.1.3 Application Curve

#### 9.2.1.3.1 System-Level Phase Noise and Additive Jitter Measurement



**Figure 11. 40-MHz Input Phase Noise (181 fs rms, Light Blue), and Output Phase Noise (196 fs rms, Dark Blue), Additive Jitter = 77 fs rms**

## Typical Applications (continued)

### 9.2.2 Input Detail

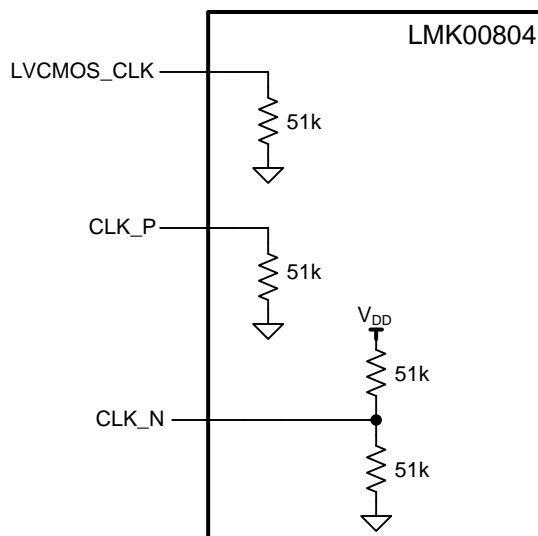


Figure 12. Clock Input Components

### 9.2.3 Input Clock Interface Circuits

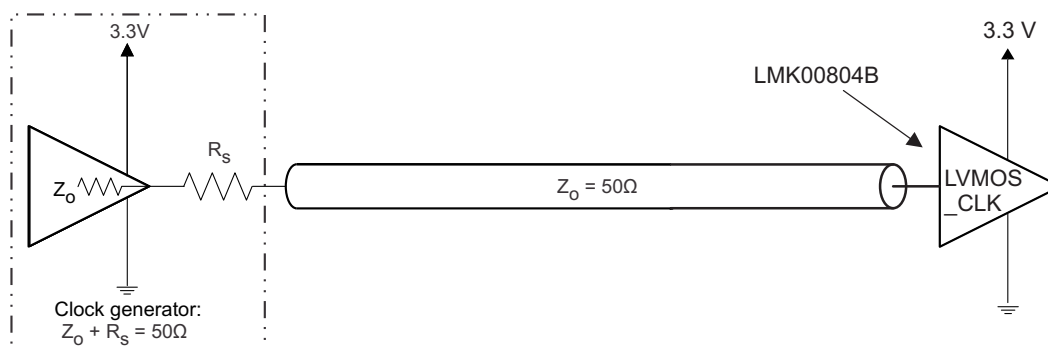
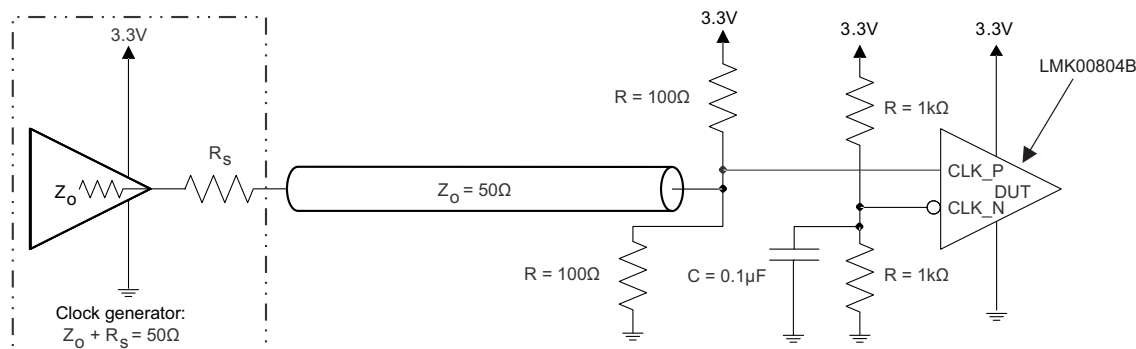


Figure 13. LVCMOS\_CLK Input Configuration



- (1) The Thevenin/split termination values ( $R = 100\ \Omega$ ) at the CLK\_P input may be adjusted to provide a small differential offset voltage (50 mV, for example) between the CLK\_P and CLK\_N inputs to prevent input chatter if the LVCMOS driver is in a tri-state condition. For example, the engineer can use  $105\ \Omega$  1% to the 3.3-V rail and  $97.6\ \Omega$  1% to GND to receive a  $-60$ -mV offset voltage ( $V_{CLK\_N} - V_{CLK\_P}$ ). Ensure a logic low state if the LVCMOS driver enters a tri-state condition.

Figure 14. Single-Ended/LVCMOS Input DC Configuration

## 9.3 Do's and Don'ts

### 9.3.1 Power Dissipation Calculations

The following power considerations refer to the device-consumed power consumption only. The device power consumption is the sum of static and dynamic power. The dynamic power usage consists of two components:

- Power used by the device as it switches states
- Power required to charge any output load

The output load can be capacitive-only or capacitive and resistive. Use [Equation 3](#) through [Equation 5](#) to calculate the power consumption of the device:

$$P_{Dev} = P_{stat} + P_{dyn} + P_{Cload} \quad (3)$$

$$P_{stat} = (I_{DD} \times V_{DD}) + (I_{DDO} \times V_{DDO}) \quad (4)$$

$$P_{dyn} + P_{Cload} = (I_{DDO,dyn} + I_{DDO,Cload}) \times V_{DDO}$$

where:

- $I_{DDO,dyn} = C_{PD} \times V_{DDO} \times f \times n$  [mA]
- $I_{DDO,Cload} = C_{load} \times V_{DDO} \times f \times n$  [mA]

Example for power consumption of the LMK00804B-Q1: 4 outputs are switching,  $f = 100$  MHz,

$V_{DD} = V_{DDO} = 3.465$  V and assuming  $C_{load} = 5$  pF per output:

$$P_{Dev} = 90 \text{ mW} + 34 \text{ mW} = 124 \text{ mW} \quad (6)$$

$$P_{stat} = (21 \text{ mA} \times 3.465 \text{ V}) + (5 \text{ mA} \times 3.465 \text{ V}) = 90 \text{ mW} \quad (7)$$

$$P_{dyn} + P_{Cload} = (2.8 \text{ mA} + 6.9 \text{ mA}) \times 3.465 \text{ V} = 34 \text{ mW} \quad (8)$$

$$I_{DD,dyn} = 2 \text{ pF} \times 3.465 \text{ V} \times 100 \text{ MHz} \times 4 = 2.8 \text{ mA} \quad (9)$$

$$I_{DD,Cload} = 5 \text{ pF} \times 3.465 \text{ V} \times 100 \text{ MHz} \times 4 = 6.9 \text{ mA} \quad (10)$$

#### NOTE

For dimensioning the power supply, consider the total power consumption. The total power consumption is the sum of device power consumption and the power consumption of the load.

### 9.3.2 Thermal Management

For reliability and performance reasons, limit the die temperature to a maximum of 125°C. That is, as an estimate,  $T_A$  (ambient temperature) plus device power consumption times  $R_{\theta JA}$  should not exceed 125°C.

Assuming the conditions in the [Power Dissipation Calculations](#) section and operating at an ambient temperature of 70°C with all outputs loaded, [Equation 11](#) shows the estimate of the LMK00804B-Q1 junction temperature:

$$T_J = T_A + P_{Total} \times R_{\theta JA} = 70^\circ\text{C} + (124 \text{ mW} \times 48^\circ\text{C/W}) = 70^\circ\text{C} + 6.0^\circ\text{C} = 76.0^\circ\text{C} \quad (11)$$

Here are some recommendations to improve heat flow away from the die:

- Use multi-layer boards
- Specify a higher copper thickness for the board
- Increase the number of vias from the top level ground plane under and around the device to internal layers and to the bottom layer with as much copper area flow on each level as possible
- Apply air flow
- Leave unused outputs floating



## Do's and Don'ts (continued)

### 9.3.3 Recommendations for Unused Input and Output Pins

- **CLK\_SEL and CLK\_EN:** CLK\_EN must be held low until a valid reference clock is provided before the engineer can use the pin to enable the outputs. These inputs both have an internal pullup (PU) according to [Table 1](#). [Table 1](#) shows the default floating state of these inputs:

**Table 1. Input Floating Default States**

INPUT	FLOATING STATE SELECTION
CLK_SEL	CLK_P/CLK_N selected
CLK_EN	Synchronous outputs enable

- **CLK\_P/CLK\_N Inputs:** See [Figure 12](#) for the internal connections. When using a single-ended input, take note of the internal pullup and pulldown to make sure the unused input is properly biased. To interface a single-ended input to the CLK\_P/CLK\_N input, the configuration shown in [Figure 14](#) is recommended.
- **LVC MOS\_CLK Input:** See [Figure 12](#) for the internal connection. The internal pulldown (PD) resistor ensures a low state when this input is left floating.
- **Outputs:** Any unused output may be left floating.

### 9.3.4 Input Slew Rate Considerations

LMK00804B-Q1 employs high-speed and low-latency circuit topology to allow ultra-low additive jitter/phase noise and high-frequency operation. To take advantage of these benefits in the system application, it is optimal for the input signal to have a high slew rate of 3 V/ns or greater. Driving the input with a slower slew rate can degrade the additive jitter and noise floor performance. For this reason, a differential signal input is recommended over a single-ended signal, because a differential signal typically provides a higher slew rate and common-mode-rejection.

## 10 Power Supply Recommendations

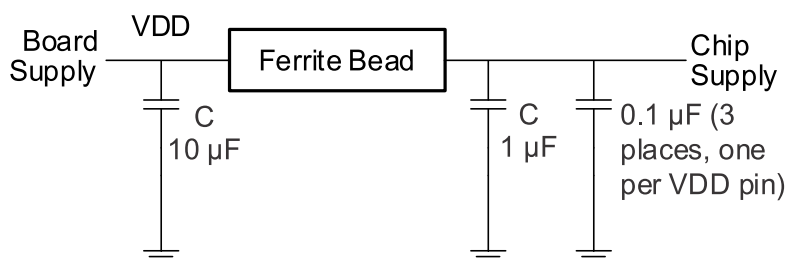
### 10.1 Power Supply Considerations

While there is no strict power supply sequencing requirement, it is generally best practice to sequence the supply input voltage ( $V_{DD}$ ) before the supply output voltage ( $V_{DDO}$ ).

#### 10.1.1 Power-Supply Filtering

High-performance clock buffers are sensitive to noise on the power supply, which can dramatically increase the additive jitter of the buffer. Thus, it is essential to reduce noise from the system power supply, especially when jitter or phase noise is critical to applications.

The use of bypass capacitors eliminates the low-frequency noise from power supply, because they can provide a very low-impedance path for high-frequency noise and guard the power-supply system against induced fluctuations. The bypass capacitors also provide instantaneous current surges as required by the device, and should have low ESR. To use the bypass capacitors properly, place them close to the power supply terminals and lay out traces with short loops to minimize inductance. TI recommends that the engineer add as many high-frequency (for example, 0.1- $\mu$ F) bypass capacitors as there are supply terminals in the package. TI recommends that the engineer insert a ferrite bead between the board power supply and the chip power supply to isolate the high-frequency switching noises generated by the clock driver. This would prevent leakage into the board supply. It is important to choose an appropriate ferrite bead with low DC resistance, because the bead must provide adequate isolation between the board supply and the chip supply. It is also important to maintain a voltage at the supply terminals that is greater than the minimum voltage required for proper operation.



**Figure 15. Power-Supply Decoupling**

## 11 Layout

### 11.1 Layout Guidelines

#### 11.1.1 Ground Planes

Solid ground planes are recommended because these planes provide a low-impedance return paths between the device and bypass capacitors, along with the clock source and destination devices.

LMK00804B-Q1 has a die attach pad (DAP) for enhanced thermal and electrical performance. Use five VIAs to connect the DAP to a solid GND plane. Full-through VIAs are preferred.

Avoid return paths of other system circuitry (for example, high-speed/digital logic, switching power supplies, and so forth) from passing through the local ground of the device to minimize noise coupling. Remember that noise coupling can lead to added jitter and spurious noise.

#### 11.1.2 Power Supply Pins

Follow the power supply schematic and layout example described in [Power-Supply Filtering](#).

## Layout Guidelines (continued)

### 11.1.3 Differential Input Termination

- Place input termination or biasing resistors as close to the CLK\_P/CLK\_N pins as possible.
- Avoid or minimize vias in the 50-Ω input traces to minimize impedance discontinuities. Intra-pair skew should also be minimized on the differential input traces.
- If not used, CLK\_P/CLK\_N inputs may be left as no connect.

### 11.1.4 LVCMOS Input Termination

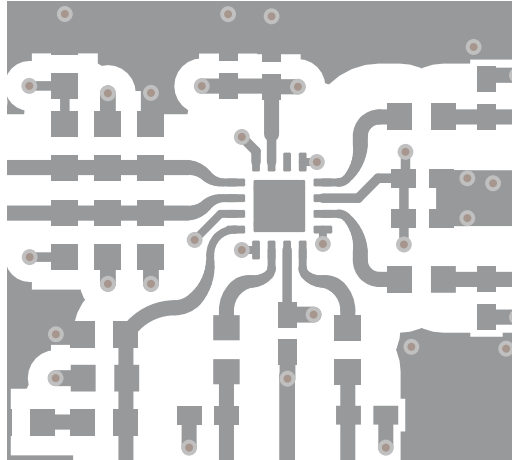
- Input termination is not necessary when the LVCMOS\_CLK input is driven from a LVCMOS driver that is series-terminated to match the characteristic impedance of the trace. Otherwise, place the input termination resistor as close to the LVCMOS\_CLK input as possible.
- Avoid or minimize vias in the 50-Ω input trace to minimize impedance discontinuities.
- If not used, LVCMOS\_CLK input may be left as no connect.

### 11.1.5 Output Termination

- Place 43-Ω series termination resistors close to the Qx outputs at the launch of the 50-Ω traces.
- Avoid or minimize vias in the 50-Ω input traces to minimize impedance discontinuities.
- If not used, any Qx output should be left as no connect.

## 11.2 Layout Example

Figure 16 shows the recommended PCB design for good electrical and thermal performance. To maximize the heat dissipation from the package, a thermal landing pattern including multiple vias to a ground plane must be incorporated into the PCB within the footprint of the package. The thermal pad must be soldered down to ensure adequate heat conduction to of the package. Refer to the *Example Board Layout* in the *Package Option Addendum*.



**Figure 16. General PCB Ground Layout for Thermal Reliability**

## 12 Device and Documentation Support

### 12.1 Documentation Support

#### 12.1.1 Related Documentation

For related documentation, see the following:

[High-Speed Layout Guidelines](#) (SCAA082)

### 12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 12.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 12.4 Trademarks

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All other trademarks are the property of their respective owners.

### 12.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 12.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">LMK00804BQWRGTRQ1</a>	Active	Production	VQFN (RGT)   16	3000   LARGE T&R	Yes	Call TI   Sn	Level-2-260C-1 YEAR	-40 to 125	804BQ
LMK00804BQWRGTRQ1.A	Active	Production	VQFN (RGT)   16	3000   LARGE T&R	Yes	Call TI	Level-2-260C-1 YEAR	-40 to 125	804BQ
<a href="#">LMK00804BQWRGTTQ1</a>	Active	Production	VQFN (RGT)   16	250   SMALL T&R	Yes	Call TI   Sn	Level-2-260C-1 YEAR	-40 to 125	804BQ
LMK00804BQWRGTTQ1.A	Active	Production	VQFN (RGT)   16	250   SMALL T&R	Yes	Call TI	Level-2-260C-1 YEAR	-40 to 125	804BQ

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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**OTHER QUALIFIED VERSIONS OF LMK00804B-Q1 :**

- Catalog : [LMK00804B](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMK00804BQWRGTRQ1	VQFN	RGT	16	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
LMK00804BQWRGTTQ1	VQFN	RGT	16	250	180.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMK00804BQWRGTRQ1	VQFN	RGT	16	3000	346.0	346.0	33.0
LMK00804BQWRGTTQ1	VQFN	RGT	16	250	210.0	185.0	35.0



**RGT 16**

**GENERIC PACKAGE VIEW**

**VQFN - 1 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4203495/1

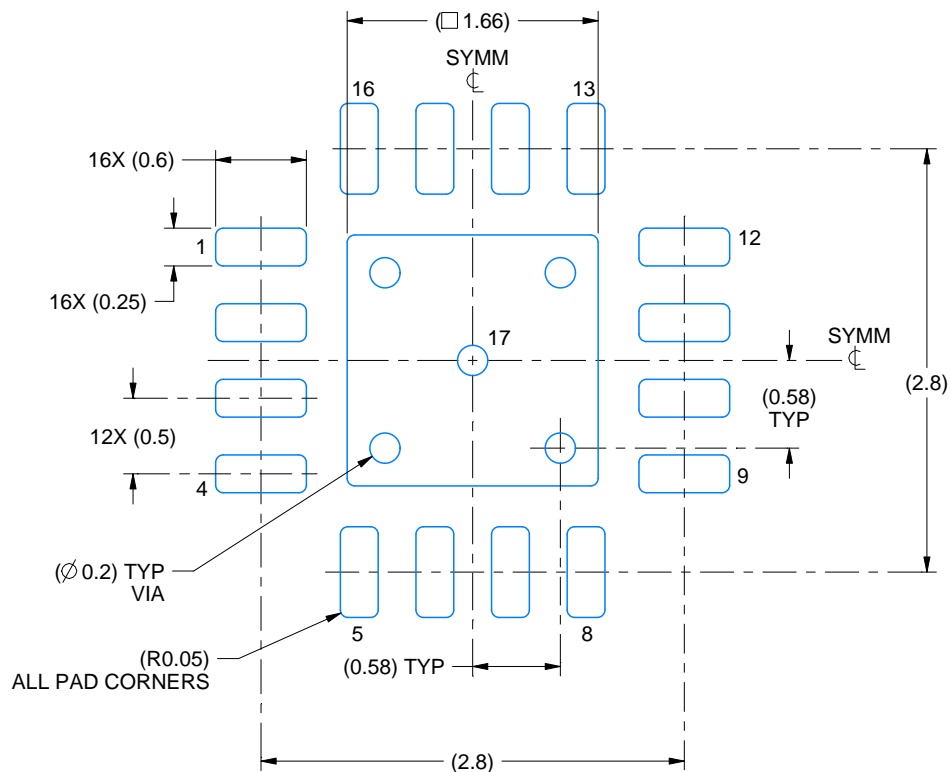
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

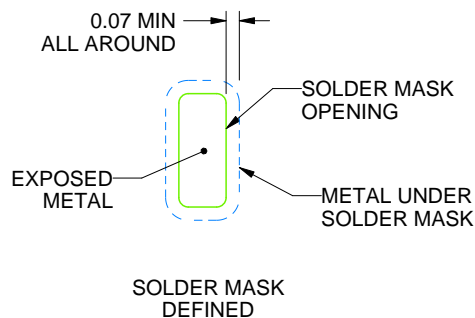
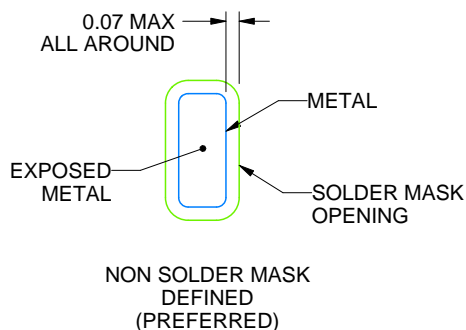
RGT0016J

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:20X



SOLDER MASK DETAILS

4224573/B 11/2018

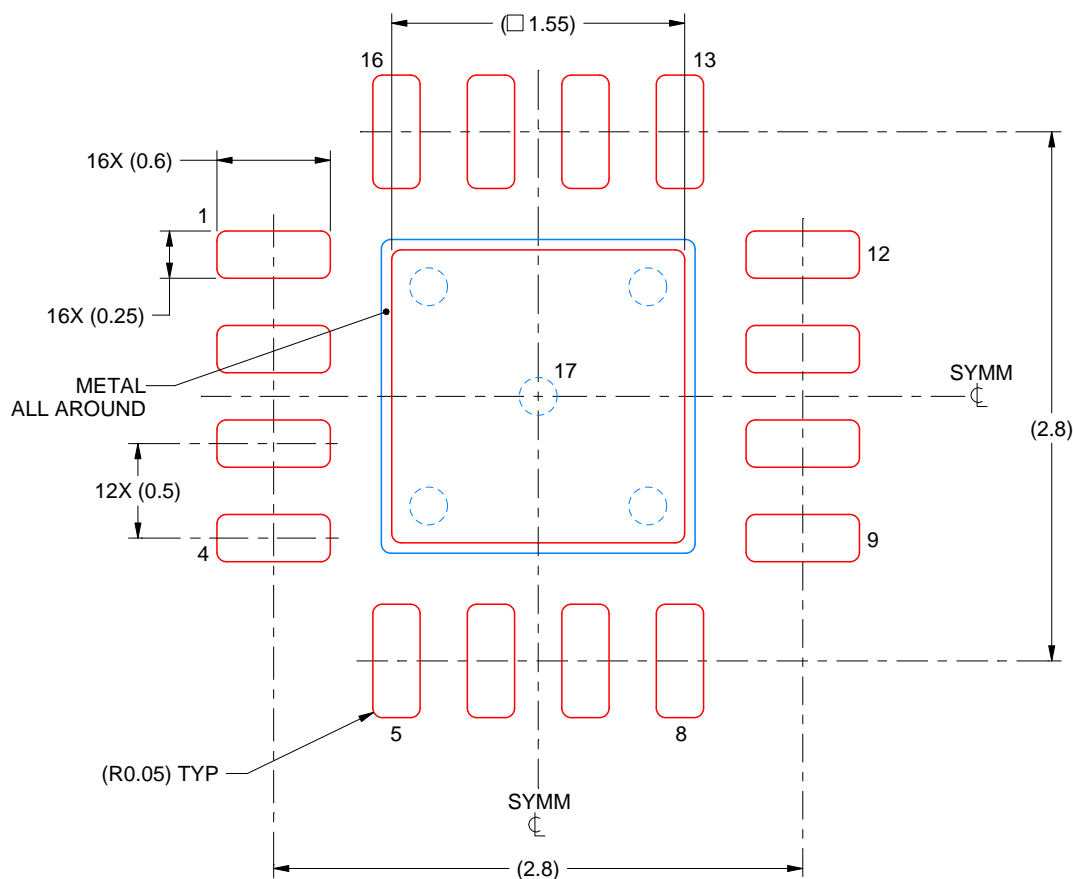
NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

**RG T0016J**

### VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



## SOLDER PASTE EXAMPLE BASED ON 0.1 mm THICK STENCIL

THERMAL PAD 17:  
87% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
SCALE:25X

4224573/B 11/2018

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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